Document Number: STBV36135AY2 Preliminary Datasheet V1.0

## Gallium Nitride 50V, 135W,3.3-3.8GHz RF Power Transistor

### **Description**

The STBV36135AY2 is a single ended 135watt, GaN HEMT, ideal for applications from 3.3 to 3.8GHz. It is an input matched transistor capable to support CW, pulse or any modulated signal.

There is no guarantee of performance when this part is used outside of stated frequencies.

Typical pulse CW and CW performance across 3.3-3.8GHz with device soldered

VDD = 50 Vdc, IDQ = 200mA, Pulse width=20us, CW Psat defined as no gate leakage current

Signal	Psat(W)	Power gain (dB)	Eff(%)@P3dB
Pulsed CW	142-185	11.5-12.5	57-62
CW	140-170	11-12	55-58

# STBV36135AY2

### **Applications**

- Sub-4GHz pulse or CW amplifier
- 5G base station amplifier
- S band Jammer

### **Important Note: Proper Biasing Sequence for GaN HEMT Transistors**

### Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically –5 V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

### Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

### **Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
DrainSource Voltage	$V_{DSS}$	+200	Vdc
GateSource Voltage	$V_{GS}$	-8 to +0.5	Vdc
Operating Voltage	$V_{DD}$	55	Vdc
Maximum gate current	lgs	20	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

### **Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA	Do 10	1.1	°C /W
T <sub>C</sub> = 25°C, at Pd=100W	Rejc	1.1	-0 /٧٧

### Table 3. Electrical Characteristics (TA = 25℃ unless otherwise noted)

### DC Characteristics (measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=20mA	$V_{DSS}$		200		V



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Gate Threshold Voltage	VDS =10V, ID = 20mA	$V_{GS(th)}$	-4	-3	-2	V
Gate Quiescent Voltage	VDS =50V, IDS=200mA, Measured in Functional Test	$V_{GS(Q)}$		-3.3		V

### **Ruggedness Characteristics**

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	3.45GHz, Pout=135W pulse CW					
	for each path	VSWR		10:1		
	All phase,	70777		10.1		
	No device damages					

Figure 2: Median Lifetime vs. Channel Temperature

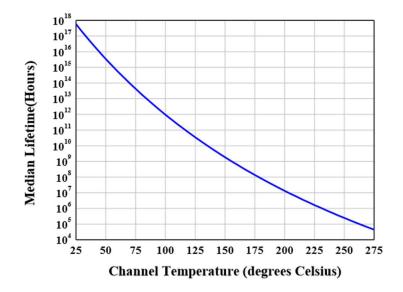


Figure 3: S11 / S21 output from network analyzer on 3.3-3.6GHz application board



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Figure 4: Picture of application board of 3.3-3.8GHz

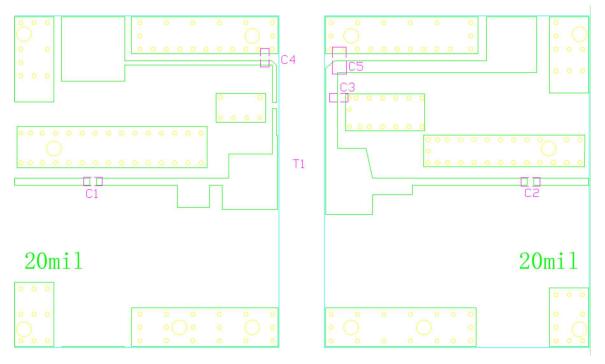
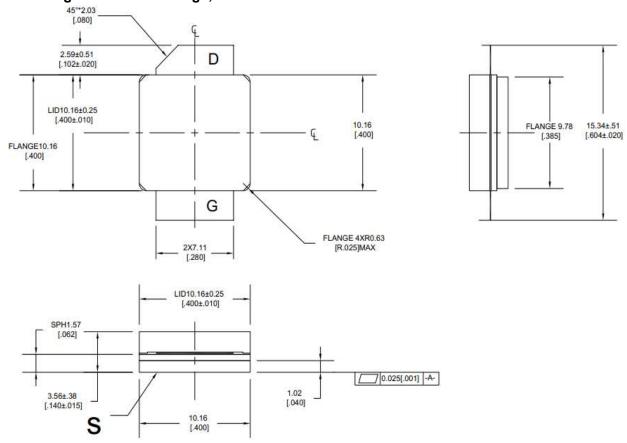


Table 4. Bill of materials of application board (PCB layout upon request, RO4350B 20mils)

		•	•	•
Part	Quantity	Description	Part Number	Manufacture
C1,C2,C3,C4	4	8.2pFHigh Q	251SHS8R2BSE	TEMEX
		Capacitor		
C5	1	10uF MLCC	GRM32EC72A106ME0	Murata
			5	
T1	1	135W GaN	STBV36135AY2	Innogration
		Dual Transistor		

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### Earless Flanged Ceramic Package; 2 leads



Unit: mm [inch]

Tolerance .xx +/- 0.01 .xxx +/- 0.005 inches



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### **Revision history**

### **Table 4. Document revision history**

Date	Revision	Datasheet Status
2024/7/2	V1.0	Preliminary datasheet creation

Application data based on: LWH-24-23

### **Notice**

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